

MOS INTEGRATED CIRCUIT  
 **$\mu$ PD6902C**

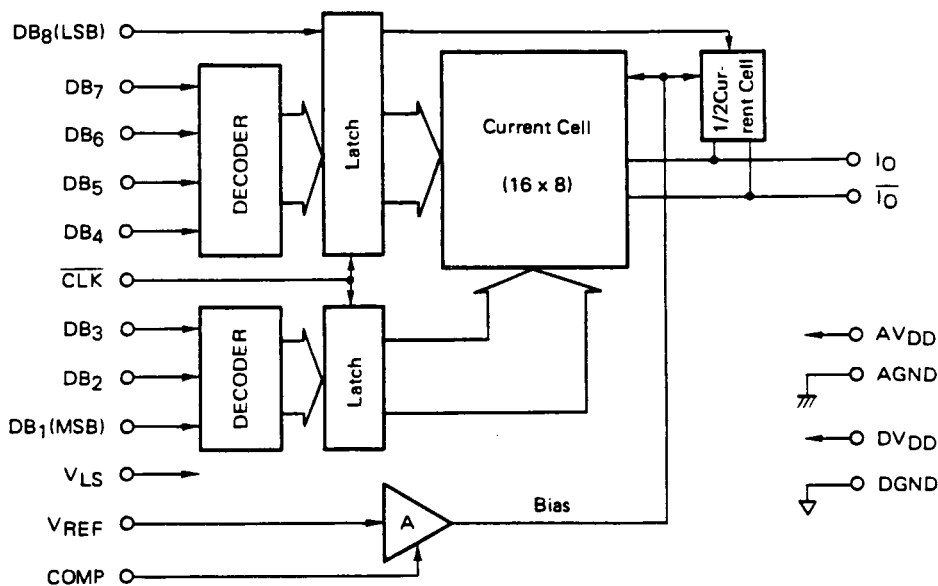
**8 bit 50MSPS D/A Converter  
CMOS**

The  $\mu$ PD6902C is an 8 bit D/A converter for use in video applications. The high-speed CMOS processing technology and the matrix current cell method adopted for this CMOS device have enabled fast conversion rates to be achieved. Conversion rates of up to 50 Msp/s can be attained while operating at low power consumption, making this device ideal for a wide range of applications including digital TV systems and video systems.

**FEATURES**

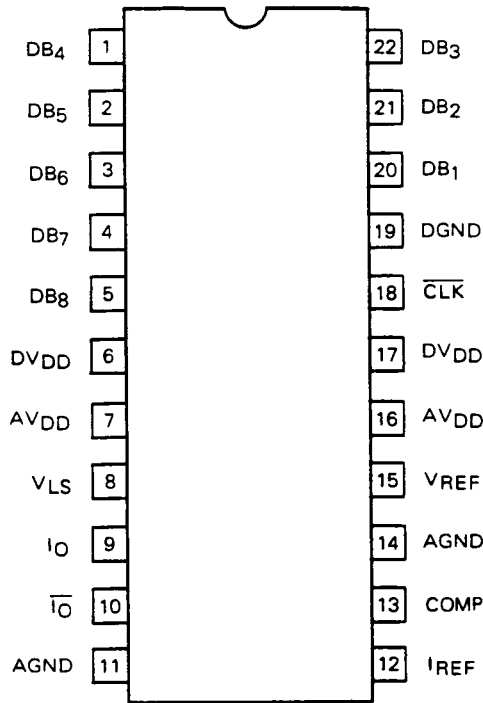
- Resolution: 8 bits
- Conversion rate: 50 Msp/s
- Linearity:  $\pm 1.0$  LSB TYP.
- Reference voltage: 2.5 V TYP.
- Power supply voltage: +5 V single
- Low power consumption (400 mW TYP.)
- TTL/CMOS selectable (Digital data input level.)
- 22 pin plastic DIP

**BLOCK DIAGRAM**



NEC cannot assume any responsibility for any circuits shown or represent that they are free from patent infringement.  
The \* mark outside the columns denotes major points where revisions or additions are made in this edition.

★ CONNECTION DIAGRAM (Top View)



- 1 DB4 Digital input (4th)
- 2 DB5 Digital input (5th)
- 3 DB6 Digital input (6th)
- 4 DB7 Digital input (7th)
- 5 DB8 Digital input (LSB)
- 6 DVDD Digital power supply
- 7 AVDD Analog power supply
- 8 VLS Digital input level select (TTL/CMOS)
- 9  $I_o$  Current output
- 10  $\bar{I}_o$  Complementary current output
- 11 AGND Analog GND
- 12 IREF Full-scale current adjustment
- 13 COMP Amp compensation
- 14 AGND Analog GND
- 15 VREF Reference voltage input
- 16 AVDD Analog power supply
- 17 DVDD Digital power supply
- 18  $\bar{CLK}$  Sampling clock input
- 19 DGND Digital GND
- 20 DB1 Digital input (MSB)
- 21 DB2 Digital input (2nd)
- 22 DB3 Digital input (3rd)

**ABSOLUTE MAXIMUM RATINGS (T<sub>a</sub> = 25 °C)**

Power supply voltage	-0.3 to +7.0	V
Input terminal voltage	-0.3 to AV <sub>DD</sub> +0.3 or DV <sub>DD</sub> +0.3	V
Output terminal voltage	-0.3 to AV <sub>DD</sub> +0.3 or DV <sub>DD</sub> +0.3	V
Analog power supply voltage	DV <sub>DD</sub> -0.3 to DV <sub>DD</sub> +0.3	V
Analog GND voltage	DGND-0.3 to DGND+0.3	V
Operating temperature range	-20 to +75	°C
Storage temperature range	-40 to +125	°C

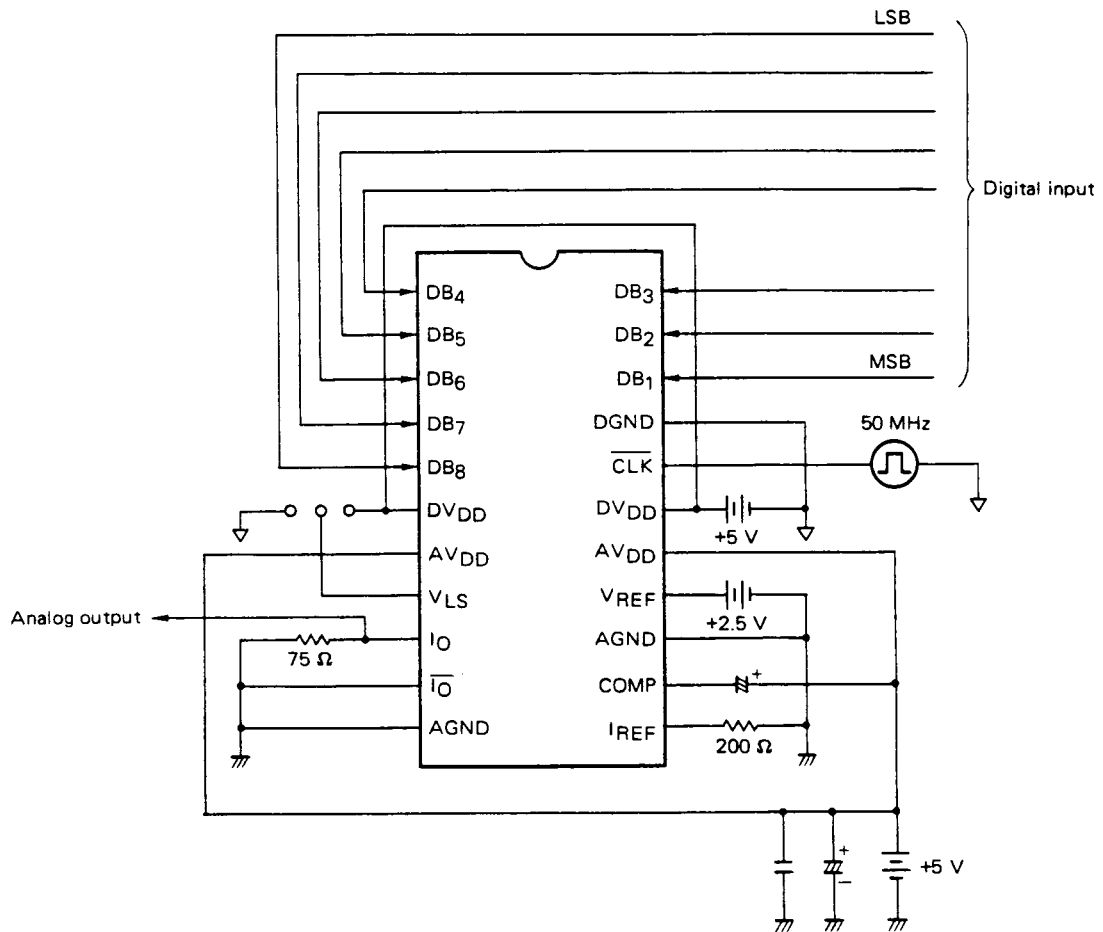
**RECOMMENDED OPERATING CONDITIONS (T<sub>a</sub> = -20 to +75 °C)**

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Power supply voltage	AV <sub>DD</sub> , DV <sub>DD</sub>	4.75	5.0	5.25	V	
Reference voltage	V <sub>REF</sub>		2.5		V	
Reference resistance	R <sub>REF</sub>		200		Ω	
Sampling clock	f <sub>samp</sub>	0.1		50	MHz	
Sampling clock low level pulse width	t <sub>PWL</sub>	8			ns	
Sampling clock high level pulse width	t <sub>PWH</sub>	8			ns	
Data set up time	t <sub>S</sub>	8			ns	
Data hold time	t <sub>H</sub>	5			ns	
Digital input high level 1	V <sub>IH1</sub>	2.7			V	V <sub>LS</sub> =GND
Digital input low level 1	V <sub>IL1</sub>			0.6	V	V <sub>LS</sub> =GND
Digital input high level 2	V <sub>IH2</sub>	0.7V <sub>DD</sub>			V	V <sub>LS</sub> =DV <sub>DD</sub>
Digital input low level 2	V <sub>IL2</sub>			0.3V <sub>DD</sub>	V	V <sub>LS</sub> =DV <sub>DD</sub>
Compensation capacity	C <sub>comp</sub>		1.0		μF	

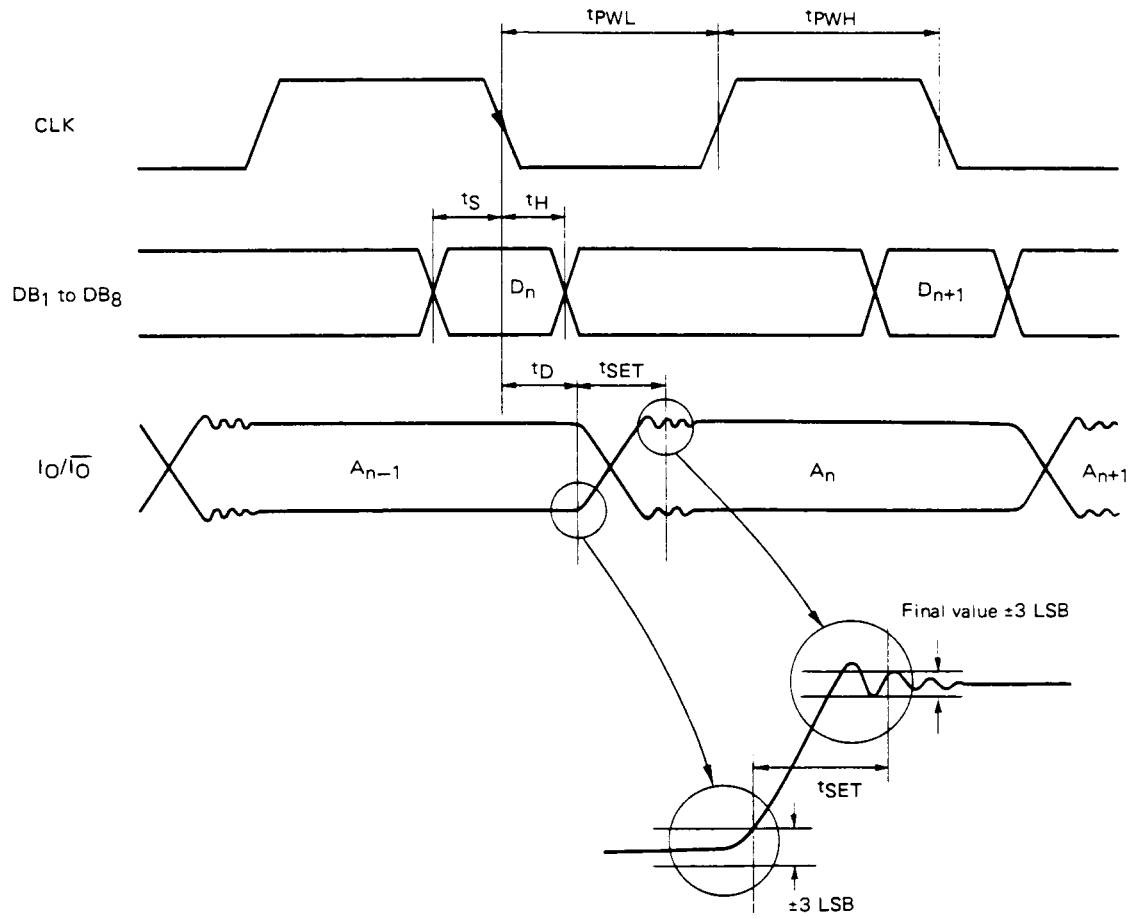
**ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = -20 to +75 °C, V<sub>DD</sub> = 5 V ±0.25 V, f<sub>samp</sub> = 50 MHz)**

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION
Power supply current	I <sub>DD</sub>		100	160	mA	f <sub>samp</sub> =50 MHz, T <sub>a</sub> =25 °C, V <sub>CC</sub> =5.25 V
Resolution	RES		8		bit	
Non-linearity error	NL		±0.25	±1	LSB	T <sub>a</sub> =0 to 60 °C, V <sub>DD</sub> =5 V
Differential non-linearity	DNL		±0.25	±0.5	LSB	T <sub>a</sub> =0 to 60 °C, V <sub>DD</sub> =5 V
Output compliance	V <sub>O</sub>	1.0	1.5		V	V <sub>DD</sub> =5.0±0.25 V, T <sub>a</sub> =0 to 70 °C
Full-scale current	I <sub>FS</sub>	18	20.4	22	mA	V <sub>REF</sub> =2.5 V, R <sub>REF</sub> =200 Ω
Settling time	t <sub>SET</sub>		32		ns	Final I <sub>O</sub> value ≤ ±3 LSB
Analog output delay time	t <sub>D</sub>		12		ns	I <sub>O</sub> value ≤ ±3 LSB

★ TEST CIRCUIT



TIMING CHART



**PIN DESCRIPTIONS**

- DGND (Pin 19) Digital system ground
- AGND (Pins 11, 14) Analog system ground
- DV<sub>DD</sub> (Pins 6, 17) Digital system power supply (+5 V)
- AV<sub>DD</sub> (Pins 7, 16) Analog system power supply (+5 V)

The digital system power supply and ground is isolated from the analog system power supply and ground in the IC as a precaution against noise. The ground and power supply lines are also isolated on the circuit boards, the analog ground being as wide as possible for better stability.

Insert by-pass capacitors of about 0.01 μF and 47 μF between the analog power line and analog ground, and also between the digital power line and digital ground. These capacitors should be connected as close as possible to the μPD6902C pins. Supply the digital system power from the analog power line through the low path filter to prevent from lurch up.

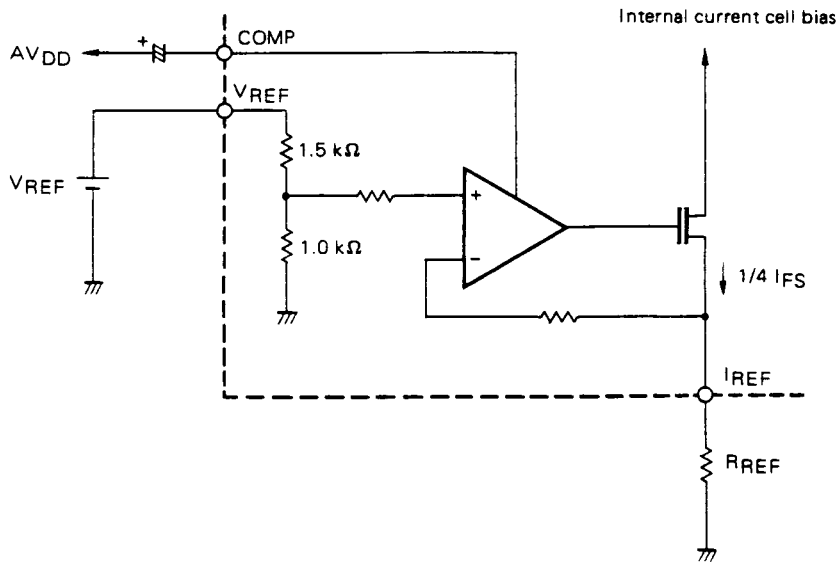
- I<sub>REF</sub> (Pin 12) Full-scale current adjustment pin
- V<sub>REF</sub> (Pin 15) Reference voltage input pin

These pins are used in adjustment of the analog output current (full-scale current).

The analog output current (full-scale current I<sub>FS</sub>) is set by the reference voltage V<sub>REF</sub> and the reference resistance R<sub>REF</sub> connected between the I<sub>REF</sub> pin and analog ground.

$$I_{FS} = \frac{4}{2.5} V_{REF} / R_{REF}$$

$$I_{REF} = \frac{1}{2.5} V_{REF} / R_{REF}$$



The recommended reference voltage and reference resistance values are V<sub>REF</sub> = 2.5 V and R<sub>REF</sub> = 200 Ω respectively. The output analog current I<sub>FS</sub> in this case will be 20 mA. Also connect by-pass capacitors of about 0.01 μF and 47 μF between the V<sub>REF</sub> pin and AGND in the same way as the by-pass capacitors connected to the power pins.

- COMP (Pin 13) Phase compensation capacitor connection

A capacitor for phase compensation of the internal amplifier is connected to this pin. Connect a 1.0 μF capacitor between this pin and analog V<sub>DD</sub>.



DB<sub>1</sub> to DB<sub>8</sub> (Pins 20 to 22, Pins 1 to 5) Digital data input pins  
 DB<sub>1</sub> to DB<sub>8</sub> are the 8 bit digital data input pins. The code format is binary.

Digital input code								Analog output current
DB <sub>1</sub> (MSB)	DB <sub>2</sub>	DB <sub>3</sub>	DB <sub>4</sub>	DB <sub>5</sub>	DB <sub>6</sub>	DB <sub>7</sub>	DB <sub>8</sub> (LSB)	
0	0	0	0	0	0	0	0	0 note
0	0	0	0	0	0	0	1	1/256 I <sub>FS</sub>
⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮	⋮
1	1	1	1	1	1	0	1	253/256 I <sub>FS</sub>
1	1	1	1	1	1	1	0	254/256 I <sub>FS</sub>
1	1	1	1	1	1	1	1	255/256 I <sub>FS</sub>

**note** : Excluding offset current

Digital data (DB<sub>1</sub> to DB<sub>8</sub>) is latched by the falling edge of the sampling clock, and converted to corresponding analog outputs.

**CLK** (Pin 18) Sampling clock input pin

Digital data is latched by the **falling edge** of the clock signal applied to the sampling clock input pin, and is subsequently converted to analog outputs. The maximum clock frequency is 50 MHz.

**I<sub>O</sub>** (Pin 9) Analog signal output pin

**I<sub>O</sub>** (Pin 10) Complementary current output pin of I<sub>O</sub> pin

These two pins are current output pins. The full-scale output current is determined by the reference resistance R<sub>REF</sub> and reference voltage V<sub>REF</sub>.

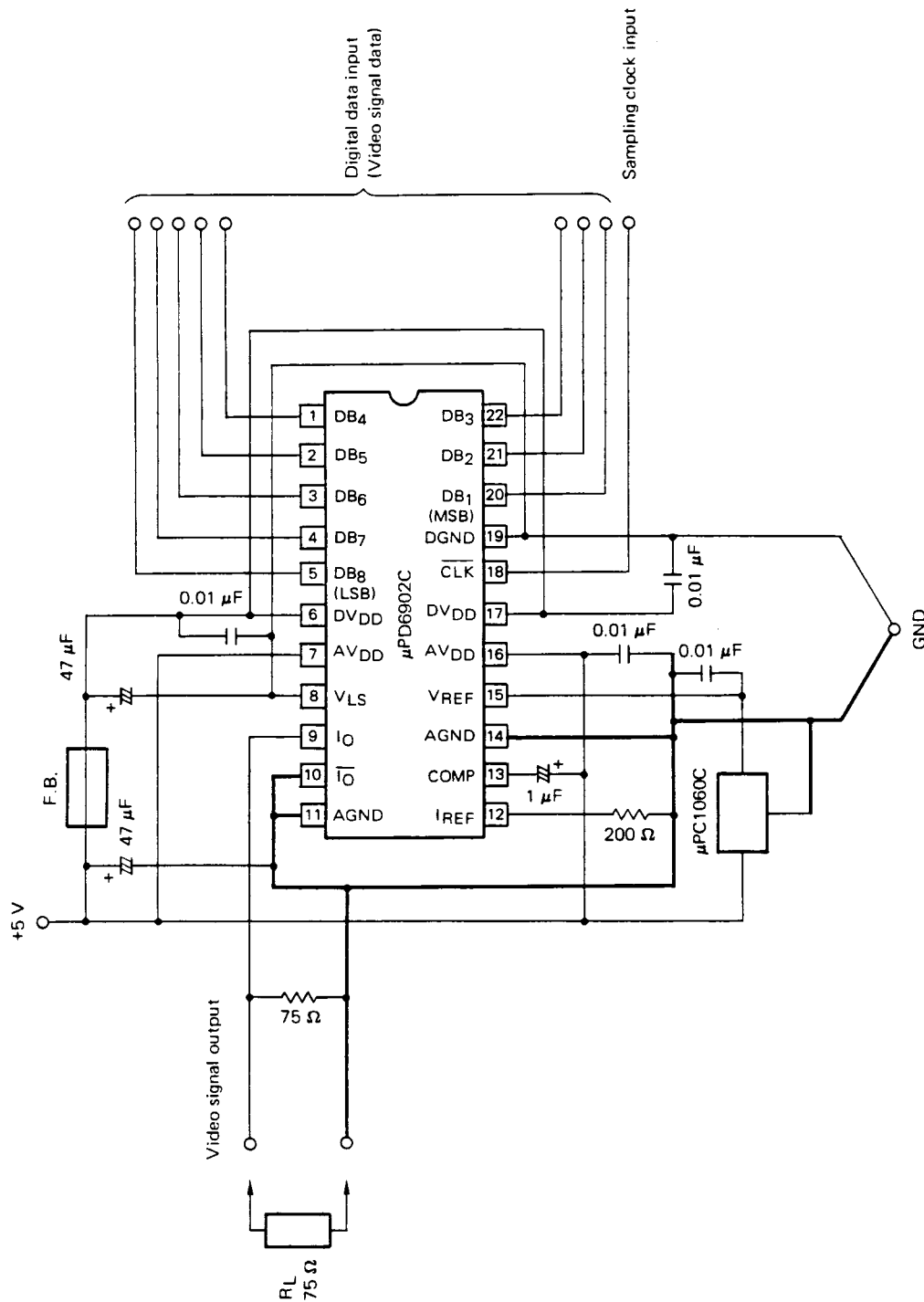
$$I_{FS} = I_O + \overline{I_O} = \frac{4}{2.5} V_{REF} / R_{REF}$$

$\overline{I_O}$  is the complementary current output pin of I<sub>O</sub>. The added output current from the I<sub>O</sub> and  $\overline{I_O}$  pins becomes the full-scale current in accordance with the above equation. Analog output current can be easily converted to an analog output voltage by connecting a resistance between the I<sub>O</sub> pin and analog ground.  $\overline{I_O}$  pin cannot use for a complementary analog voltage output, because the compliance voltage of  $\overline{I_O}$  pin is very low. Then connect  $\overline{I_O}$  pin to the AGND directly.

**V<sub>LS</sub>** (Pin 8) Digital input level select pin

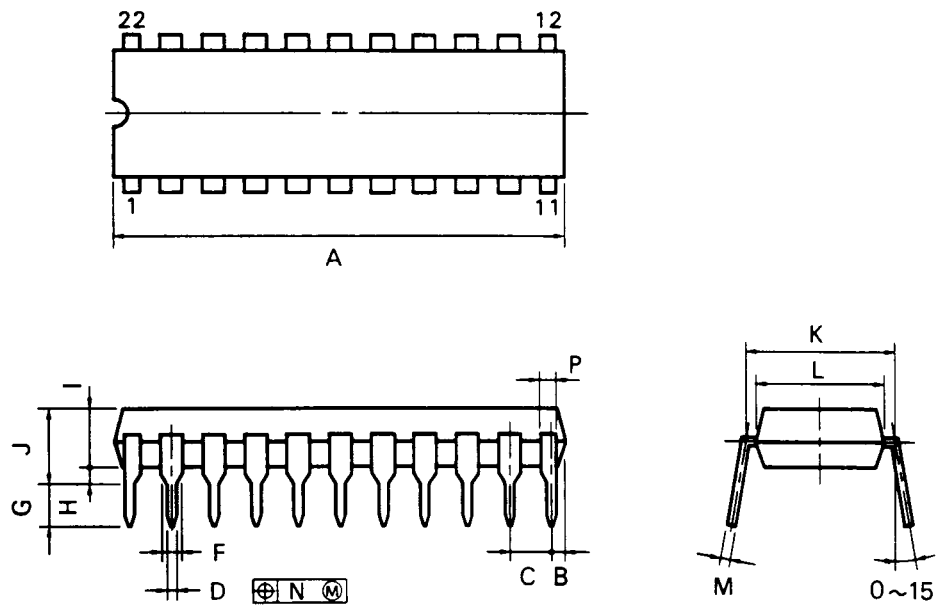
This pin is used for digital input level selection. If connect to the GND the input level becomes TTL level, and to V<sub>DD</sub> it becomes CMOS level.

★ APPLICATION CIRCUIT



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22PIN PLASTIC DIP (400 mil)



P22C-100-400B

NOTES

- 1) Each lead centerline is located within 0.25 mm (0.01 inch) of its true position (T.P.) at maximum material condition.
- 2) Item "K" to center of leads when formed parallel.

ITEM	MILLIMETERS	INCHES
A	27.94 MAX.	1.100 MAX.
B	1.27 MAX.	0.050 MAX.
C	2.54 (T.P.)	0.100 (T.P.)
D	0.50 $\pm 0.10$	0.020 $\pm 0.004$
F	1.2 MIN.	0.047 MIN.
G	3.5 $\pm 0.3$	0.138 $\pm 0.012$
H	0.51 MIN.	0.020 MIN.
I	4.31 MAX.	0.170 MAX.
J	5.72 MAX.	0.226 MAX.
K	10.16 (T.P.)	0.400 (T.P.)
L	8.6	0.339
M	0.25 $\pm 0.10$	0.010 $\pm 0.004$
N	0.25	0.01
P	0.8 MIN.	0.031 MIN.